2SD893, 2SD893A

Silicon NPN epitaxial planer type darlington

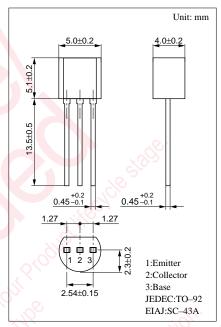
For low-frequency amplification

Features

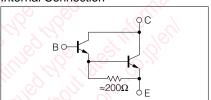
- Forward current transfer ratio h_{FE} is designed high, which is appropriate to the driver circuit of motors and printer hammer: h_{FE} = 4000 to 20000.
- A shunt resistor is omitted from the driver.

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Ratings	Unit	
Collector to	2SD893	77	30	v	
base voltage	2SD893A	V_{CBO}	60		
Collector to	2SD893	77	25	77	
emitter voltage	2SD893A	V_{CEO}	50	V	
Emitter to base voltage		V_{EBO}	5	V	
Peak collector current		I_{CP}	1.5	A	
Collector current		$I_{\rm C}$	1	A	
Collector power dissipation		P _C	0.75	W	
Junction temperature		$T_{\rm j}$	150	%.C.	
Storage temperature		$T_{\rm stg}$	−55 ~ +150	°C	



Internal Connection



Electrical Characteristics (Ta=25°C)

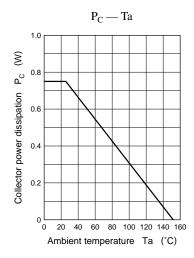
Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff	2SD893	is	$V_{CB} = 25V, I_{E} = 0$	70.7		100	_
current	2SD893A	I_{CBO}	$V_{CB} = 45V, I_{E} = 0$			100	nA
Emitter cutoff curren	t all	I _{EBO}	$V_{EB} = 4V, I_C = 0$			100	nA
Collector to base	2SD893	- V _{CBO}	$I_{C} = 100 \mu A, I_{B} = 0$	30			V
voltage	2SD893A			60			
Collector to emitter	2SD893	**		25			***
voltage	2SD893A	V _{CEO}	$I_{C} = 1 \text{mA}, I_{B} = 0$	50			V
Emitter to base voltage	ge	V_{EBO}	$I_E = 100 \mu A, I_C = 0$	5			V
Forward current transfer ratio		h _{FE} *1	$V_{CE} = 10V, I_{C} = 1A^{*2}$	4000		20000	
Collector to emitter saturation voltage $V_{CE(si)}$		V _{CE(sat)}	$I_C = 1A, I_B = 1mA$			1.8	V
		V _{BE(sat)}	$I_C = 1A$, $I_B = 1mA$			2.2	V
Transition frequency		f_T	$V_{CB} = 10V, I_E = -50mA, f = 200MHz$		150		MHz

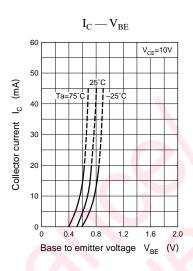
^{*2} Pulse measurement

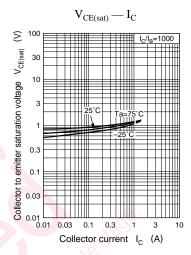
^{*1}hFE Rank classification

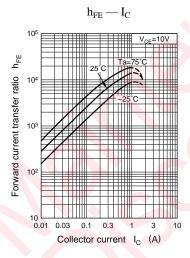
Rank	Q	R		
h_{FE}	4000 ~ 10000	8000 ~ 20000		

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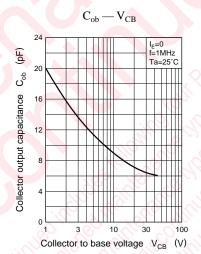








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